

AMENDMENTS TO THE CLAIMS

Please cancel claims 1-7 and 10 (claims 8-9 were cancelled). A listing of the present claims follows:

1-10. (Cancelled)

11. (Original) A method of applying thermal adhesive to an electronics assembly comprising:

forming a plurality of pre-cure thermal adhesive members;

curing said plurality of pre-cure thermal adhesive members;

applying a post-cure thermal adhesive;

assembling an electronics assembly including a heat generating component and a heat sink such that said plurality of pre-cure thermal adhesive members and said post-cure thermal adhesive are positioned within a gap formed between said heat generating component and said heat sink; and

curing said post-cure thermal adhesive.

12. (Original) A method as described in claim 11 wherein said plurality of pre-cure thermal adhesive members are formed on said heat generating component.

13. (Original) A method as described in claim 11 wherein said plurality of pre-cure thermal adhesive members are formed in said heat sink.

14. (Original) A method as described in claim 11 wherein said heat generating component is an electrical component.

15. (Original) A method as described in claim 11 wherein said forming a plurality of pre-cure thermal adhesive members includes forming droplets of pre-cure thermal adhesive.

16. (Original) A method as described in claim 11 wherein said post-cure thermal adhesive is applied to said heat generating component.

17. (Original) A method as described in claim 11 wherein said post-cure thermal adhesive is applied to said heat sink.